Type YD

Order Number LBWA1ZVYDZ

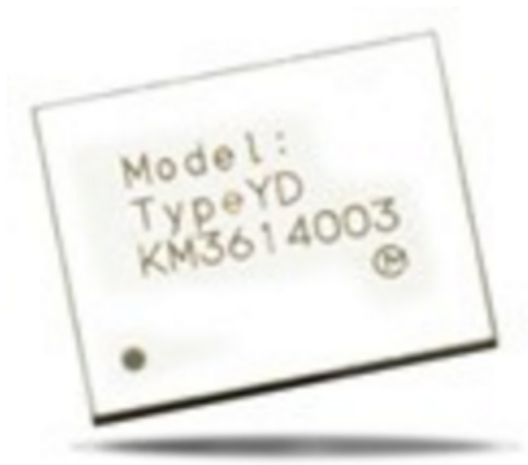
Size-Optimized Wi-Fi + MCU

- 2.4GHz Wi-Fi Module
- Network Topology: AP & STA dual mode
- Chipset: BCM43362 + STM32 ARM Cortex-M3
- Processor: STM32 ARM Cortex-M3

Feature rich software hosted on module

- Wi-Fi driver, TCP/IP stack and security supplicant
- Broadcom WICED SDK

Recommended Available



Add to Compare List

Description | **Specs** | Documents | Software | FAQ | Purchase | Contact Us

Annual Volume	50000
Product Type	Module
Grade	Consumer
Frequency	2.4GHz
Chipset	BCM43362 + STM32 ARM Cortex-M3
Processor	STM32 ARM Cortex-M3
Modulation	No
Antenna	External
RF Conn/ Antenna	Not Included
System Clock	Internal X'tal
Operating Temperature °C (min)	-40
Operating Temperature °C (max)	+85
Mounting Type	SMT
Package	LGA
Dimension	10.0 x 7.9 x 1.25 mm
Supply Voltage (Vdc)	3.3
Transmit Power	+17dBm
Receiver Sensitivity	-87dBm @ 11Mb/s
Transmit Mode Current	365mA @ +17dBm or 440mA @ +19dBm (11Mb/s)
Receive Mode Current	160mA
Data Rate WLAN	11, 54, 64 Mbps
Bluetooth	No
WLAN	802.11b/g/n
Technology	Wi-Fi
Network	AP & STA dual mode
Host Interface	UART
Host Interface Other	No
Interface Voltage (Vdc for VIO)	2.4 to 3.6
FCC/IC Certified	FCC/IC "Reference" Certified
ETSI Certified	Yes
RoHs Compliant	Yes
ISO9001	No
TS16969	No
Certification	• CE (Europe) EN 300328 V1.8.1 Conducted Test Report available Note: CE marking and declaration should be done by customer as a final product.

Related Links

- Applications for Wireless
- Support for Wireless
- Wireless Modules for IoT Applications
- Wi-Fi/Bluetooth Modules for NXP i.MX

Related Product Categories

- « Go Back
- 802.15.4
- Bluetooth & BluetoothSmart
- Wi-Fi
- Wi-Fi + Bluetooth
- HyperMesh / FHSS
- Wi-Fi Bluetooth for NXP i.MX
- Cloud Connectivity
- M2M & Sensor Networking
- Wireless Network / Telemetry
- RFIC Radios
- SAW Radios
- Resonators
- Filters
- Frequency Control